

REMARKS

Favorable reconsideration is respectfully requested in view of the foregoing amendments and following remarks.

The rejection of claims 5-6, 8, 18 and 20-26 under 35 U.S.C. § 102(e) as anticipated by Cheung et al. has been maintained.

In addition, the rejection of claim 7, 19, 27-32 and 33-35 under 35 U.S.C. § 103(a) as unpatentable over Cheung et al. in view of Kikuchi et al. has been maintained.

On page 5 of the Action, the Examiner states that the rejections have been maintained on the basis that "considering the comprising language in the preamble of the claim, and the description cited on page 6, lines 2-8 which states that the complexing agent does not contain alkali metals, the Examiner maintains the rejection based upon the fact that the specific EDTA 4H is not claimed in the independent claim and the reference does not speak to the issue of alkaline metals, which would enable, in a broad interpretation, the family of EDTA to be used in the invention. Additionally, considering the comprising language, and using a broad interpretation of the claim language, some of the solution does not contain endocrine disruptors."

The Examiner appears to be concerned about the possibility that the claim is still open to include alkaline metals and endocrine disruptors.

Claims 5 and 18 have accordingly been amended to make clear that the method of forming a copper innerconnection on a semiconductor device is conducted without any alkaline metals and endocrine disruptors.

The claims are now believed to clearly distinguish over the cited references, which teach electroless copper plating liquids containing alkaline metals and endocrine disruptors.

Claim 5 has further been amended to include an organic alkali in the copper plating liquid.
Support is found in original claim 1.

In view of the foregoing, favorable reconsideration and allowance is solicited.

Respectfully submitted,

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November 12, 2004